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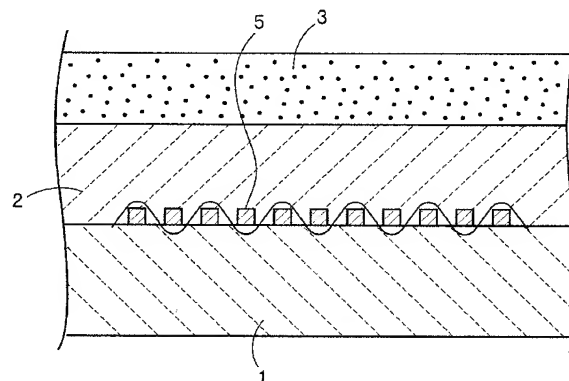
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(54) **BOUNDARY ACOUSTIC WAVE DEVICE MANUFACTURING METHOD AND BOUNDARY ACOUSTIC WAVE DEVICE**

(57) A process for producing a boundary acoustic wave device having a small variation in frequency is provided. In a process for producing a boundary acoustic wave device that includes a first medium 1, a second medium 2, and a third medium 3 laminated in that order; and electrodes 5 disposed at the interface between the first medium 1 and the second medium 2, the process includes the steps of preparing a laminate including the first medium 1, the second medium 2, and the electrodes

5 disposed at the interface between the first medium 1 and the second medium 2; adjusting the thickness of the second medium 2, after the step of preparing the laminate, to regulate a frequency or the sound velocity of a surface acoustic wave, a pseudo-boundary acoustic wave, or a boundary acoustic wave; after the adjusting step, forming the third medium 3 different from the second medium 2 in terms of the sound velocity with which the boundary acoustic wave propagates therethrough and/or in terms of material.

FIG.1



DescriptionTechnical Field

[0001] The present invention relates to a boundary acoustic wave device using a boundary acoustic wave propagating through the interface between media and a process for producing the boundary acoustic wave device. Specifically, the present invention relates to a boundary acoustic wave device having a structure including electrodes disposed between a first medium and a second medium; and another medium laminated on the outer surface of one of the first and second media, and also relates to a process for producing the boundary acoustic wave device.

Background Art

[0002] Heretofore, various surface acoustic wave devices have been used for RF and IF filters in mobile phones, resonators in VCOs, and VIF filters in television sets. The surface acoustic wave devices each use a surface acoustic wave, such as a Rayleigh wave or a first-order leaky wave, propagating along a surface of a medium.

[0003] Surface acoustic waves propagate along the surface of a medium and are thus sensitive to change in the surface condition of the medium. Accordingly, to protect the surface of the medium along which the surface acoustic waves propagate, in the related art, the surface acoustic wave element is hermetically sealed in a package having a cavity such that the surface of the medium described above is placed therein. The use of the package having the cavity inevitably increases the cost of the surface acoustic wave device. In addition, the package has significantly larger dimensions than the surface acoustic wave element; hence, the surface acoustic wave device inevitably has a large size.

[0004] Acoustic waves other than the surface acoustic waves include boundary acoustic waves propagating along the boundaries between solids.

[0005] For example, Non-Patent Document 1 discloses a boundary acoustic wave device including an IDT disposed on a 126°-rotated Y-plate X-propagating LiTaO₃ substrate and a SiO₂ film with a predetermined thickness over the IDT and the LiTaO₃ substrate. This document describes that SV + P mode boundary acoustic waves called Stoneley waves propagate. Non-Patent Document 1 also describes that when the SiO₂ film has a thickness of 1.0 λ (wherein λ represents the wavelength of the boundary acoustic wave), the electromechanical coupling coefficient is 2%.

[0006] Boundary acoustic waves propagate with their energy concentrated on the boundaries between the solids. Thus, little energy is present on the bottom surface of the LiTaO₃ substrate and a surface of the SiO₂ film. Therefore, characteristics of the boundary acoustic wave do not vary with changes in the surface state of the substrate or the thin film. Thus, a package having a cavity is unnecessary, thereby reducing the size of the acoustic wave device.

[0007] To suppress non-uniformities in resonant frequencies and center frequencies in filters and resonators using the acoustic waves, various methods for adjusting frequencies have been developed. For example, Patent Document 1 discloses, in a piezoelectric ceramic filter using the thickness vibration of a bulk wave, a method for adjusting a frequency by evaporation of an insulating material onto resonant electrodes disposed on a surface of a piezoelectric ceramic substrate.

[0008] Patent Document 2 discloses a surface wave device using a surface wave, the surface wave device including a SiN film covering interdigital electrodes and reflectors disposed on a piezoelectric substrate. A center frequency and a resonant frequency are adjusted by controlling the thickness of the SiN film.

[0009] Patent Document 3 discloses a boundary acoustic wave device shown in Fig. 12. A boundary acoustic wave device 100 includes interdigital electrodes 102 and 102 disposed on a first piezoelectric substrate 101; a dielectric film 103 over the interdigital electrodes 102 and 102; and a Si-based second substrate 104 laminated on the upper surface of the dielectric film 103. In the boundary acoustic wave device 100, the Si-based second substrate 104 is disposed on the interdigital electrodes 102 with the dielectric film 103 provided therebetween and thus is not in direct contact with the interdigital electrodes 102 and 102. Thus, it would be possible to reduce the parasitic resistance between the interdigital electrodes 102 and 102.

Non-Patent Document 1: "Piezoelectric Acoustic Boundary Waves Propagating Along the Interface between SiO₂ and LiTaO₃" IEEE Trans. Sonics and ultrason., vol. SU-25, No.6, 1978 IEEE

Patent Document 1: Japanese Unexamined Patent Application Publication No. 5-191193

Patent Document 2: Japanese Unexamined Patent Application Publication No. 2-301210

Patent Document 3: WO98/51011

Disclosure of Invention

[0010] The above-described boundary acoustic wave device does not require a package having a cavity, thereby reducing the size of an acoustic wave device. However, according to experiments conducted by the inventors, production tolerance often induced nonuniformities in a resonant frequency and a center frequency in the boundary acoustic wave

devices, as in the case of the surface acoustic wave devices. In particular, in the boundary acoustic wave device, after the formation of the electrodes on a first medium, a second medium was formed so as to cover the electrodes. Thus, if there was production tolerance in the second medium, the frequency of the boundary acoustic wave device would have been liable to vary significantly.

[0011] On the other hand, in methods described in Patent Documents 1 and 2, an insulating material is deposited on a surface of a bulk wave substrate by evaporation to adjust the frequency of a bulk wave device. In a method described in Patent Document 2, a SiN film is provided on a surface wave substrate to adjust the frequency. That is, in a known bulk wave device and surface acoustic wave device, an insulating material or a metal is deposited on a surface of a substrate to adjust a frequency by using the distribution of oscillation energy to the surface of the substrate. Furthermore, in another method, an electrode disposed on a surface of a substrate is etched or a surface of a substrate is etched to adjust a frequency.

[0012] However, since the oscillation energy of a boundary wave is negligibly distributed in a boundary acoustic wave device, such a method for adjusting the frequency cannot be employed. In other words, if foreign matter such as an insulating material is deposited on a surface of a substrate or if a surface of a substrate is etched, the resonant frequency and a pass band are not changed.

[0013] In the boundary acoustic wave device 100 described in Patent Document 3, interposing the dielectric film 103 reduces parasitic resistance. However, the frequency cannot be adjusted after completion.

[0014] In consideration of the above-described situation, it is an object of the present invention to provide a process for stably and surely producing a boundary acoustic wave device having target frequency characteristics, the process being able to efficiently suppress variation in frequency due to production tolerance. It is another object of the present invention to provide a boundary acoustic wave device having target frequency characteristics with only slight nonuniformity in frequency from lot to lot.

[0015] According to a first aspect of the present invention, in a process for producing a boundary acoustic wave device that includes a first medium, a second medium, and a third medium laminated in that order; and electrodes disposed at the interface between the first medium and the second medium, the process includes the steps of preparing a laminate including the first medium, the second medium, and the electrodes disposed at the interface between the first medium and the second medium; adjusting the thickness of the second medium after the step of preparing the laminate to regulate a frequency or the sound velocity of a surface acoustic wave, a pseudo-boundary acoustic wave, or a boundary acoustic wave; and after the adjusting step, forming the third medium different from the second medium in terms of the sound velocity with which the boundary acoustic wave propagates therethrough and/or in terms of material.

[0016] According to an embodiment of the first aspect of the present invention, the third medium has a thickness exceeding 0.5λ , where λ represents the wavelength of the boundary acoustic wave.

[0017] According to a second aspect of the present invention, in a process for producing a boundary acoustic wave device that includes a first medium, a second medium, a third medium, and a fourth medium laminated in that order; and electrodes disposed at the interface between the first medium and the second medium, the process includes the steps of preparing a laminate including the first medium, the second medium, and the third medium formed in that order and electrodes disposed at the interface between the first medium and the second medium; adjusting a frequency or the sound velocity of a surface acoustic wave, a pseudo-boundary acoustic wave, or a boundary acoustic wave after the step of preparing the laminate; and after the adjusting step, forming the fourth medium, the sound velocity in the fourth medium and/or the material of the fourth medium being different from that of the third medium.

[0018] In the first and second aspects of the present invention described above, the sound velocity in the third medium and/or the material of the third medium is different from that of the second medium, and sound velocity in the fourth medium and/or the material of fourth medium is different from the third medium. In this case, different materials result in different sound velocities of a longitudinal wave and a transverse wave. When the same material is used, it is possible to change the sound velocity by using different crystalline states or by changing the degree of density if the material is polycrystalline. Furthermore, when the medium layer is isotropic, the velocity of longitudinal waves in the medium layer, i.e., V_s , and the velocity of transverse waves, i.e., V_p , are represented by equations (1) and (2):

$$V_s = \sqrt{\frac{C_{11} - C_{12}}{2\rho}} \quad \dots (1)$$

$$V_p = \sqrt{\frac{C_{11}}{\rho}} \dots (2)$$

where C_{11} and C_{12} each represent an elastic stiffness constant; and ρ represents a density. According to an embodiment of the second aspect of the present invention, the fourth medium has a thickness exceeding 0.5λ , where λ represents the wavelength of a boundary acoustic wave.

[0019] According to another embodiment of the first or second aspect of the present invention, at least one medium has a laminated structure in which a plurality of material layers are laminated.

[0020] According to another embodiment of the first or second aspect of the present invention, the electrodes are each composed of one metal selected from the group consisting of Au, Ag, Cu, Fe, Ta, W, Ti, and Pt.

[0021] According to another embodiment of the first or second aspect of the present invention, the medium layers are each composed of at least one material selected from the group consisting of lithium niobate, potassium niobate, lithium tantalate, lithium tetraborate, langasite, langanite, quartz, lead zirconate titanate ceramics, ZnO, AlN, silicon oxides, glass, silicon, sapphire, silicon nitrides, and carbon nitrides.

[0022] According to another embodiment of the first or second aspect of the present invention, the electrodes constitute a boundary acoustic wave resonator or a boundary acoustic wave filter, and the boundary acoustic wave device is the boundary acoustic wave resonator or the boundary acoustic wave filter.

[0023] According to a third aspect of the present invention, a boundary acoustic wave device includes a first medium, a second medium, a third medium, and a fourth medium laminated in that order; and electrodes disposed at the interface between the first medium and the second medium, the sound velocity in the third medium and/or the material of the third medium being different from that of the fourth medium.

[0024] In the production process according to the first aspect of the present invention, after preparing the laminate including the first medium, the second medium, and the electrodes disposed at the interface between the first medium and the second medium, the thickness of the second medium is adjusted after the step of preparing the laminate to regulate a frequency or the sound velocity of a boundary acoustic wave. After the adjusting step, the third medium is formed, the third medium being different from the second medium in terms of the sound velocity with which the boundary acoustic wave propagates therethrough and/or in terms of material. That is, the laminate including the electrodes disposed between the first and the second media is prepared, and then the second thickness is adjusted after the step of preparing the laminate. Thereby, it is possible to regulate a frequency or the sound velocity of a surface acoustic wave, a pseudo-boundary acoustic wave, or a boundary acoustic wave. Thus, it is possible to produce a laminate for forming a boundary acoustic wave device having a target frequency. In this case, to adjust the second medium after the step of preparing the laminate to regulate the frequency or the sound velocity, the thickness of the second medium may be adjusted in producing the laminate. Alternatively, the thickness of the second medium may be changed after the completion of the laminate.

[0025] After the adjusting step, the third medium, in which the sound velocity in the third medium and/or the material of the third medium is different from that of the second medium, is formed. The energy of the boundary acoustic wave is negligibly distributed in the third medium. Thus, even if variation of the third medium from lot to lot occurs, variations in sound velocity and frequency do not easily occur. Consequently, it is possible to easily and reliably provide a boundary acoustic wave device having only slight nonuniformity in device characteristics.

[0026] In the production process according to the first aspect of the present invention, after preparing the laminate including the first medium, the second medium, and the third medium formed in that order and electrodes disposed at the interface between the first medium and the second medium, the thickness of the third medium is adjusted after the step of preparing the laminate to regulate a frequency or the sound velocity of a boundary acoustic wave. After the adjusting step, the fourth medium is formed, the sound velocity in the fourth medium and/or the material of the fourth medium being different from that of the third medium. That is, the laminate including the electrodes disposed between the first and the second media; and the third medium laminated on the second medium is prepared, and then the thickness of the third medium is adjusted after the step of preparing the laminate. Thereby, it is possible to regulate a frequency or the sound velocity of a surface acoustic wave, a pseudo-boundary acoustic wave, or a boundary acoustic wave. Thus, it is possible to produce a laminate for forming a boundary acoustic wave device having a target frequency. In this case, to adjust the third medium after the step of preparing the laminate to regulate the frequency or the sound velocity, the thickness of the third medium may be adjusted in producing the laminate. Alternatively, the thickness of the third medium may be changed after the completion of the laminate.

[0027] After the adjusting step, the fourth medium, in which the sound velocity in the fourth medium and/or the material of the fourth medium is different from that of the third medium, is formed. The energy of the boundary acoustic wave is

negligibly distributed in the fourth medium. Thus, even if variation of the fourth medium from lot to lot occurs, variations in sound velocity and frequency do not easily occur. Consequently, it is possible to easily and reliably provide a boundary acoustic wave device having only slight nonuniformity in device characteristics.

[0028] In a boundary wave propagating through the boundary acoustic wave device according to the first or second aspect of the present invention, most of the energy is distributed in the range up to 0.5λ thickness of a medium 3 in the first aspect or a medium 4 in the second aspect of the present invention. Thus, the medium 3 in the first aspect or the medium 4 in the second aspect of the present invention preferably has a thickness of 0.5λ or more.

[0029] When at least one medium has a laminated structure in which a plurality of material layers are laminated, the selection of the plurality of the material layers can easily form medium layers having different sound velocities therein or frequency characteristics.

[0030] When the electrodes are each composed of one metal selected from the group consisting of Au, Ag, Cu, Fe, Ta, W, Ti, and Pt, the metal is used as a material for the propagation path, the IDT, and the reflector of the boundary wave device.

[0031] In the medium layers each composed of at least one material selected from the group consisting of lithium niobate, potassium niobate, lithium tantalate, lithium tetraborate, langasite, langanite, quartz, lead zirconate titanate ceramics, ZnO, AlN, silicon oxides, glass, silicon, sapphire, silicon nitrides, and carbon nitrides, the thickness of the metal material and duty ratios of the IDT and the reflector are adjusted in such a manner that the sound velocity of the boundary wave is lower than those in the materials of the media, thereby producing a boundary wave device.

[0032] When the electrodes constitute a boundary acoustic wave resonator or a boundary acoustic wave filter, the boundary acoustic wave resonator or the boundary acoustic wave filter can be produced according to the present invention.

[0033] In the boundary acoustic wave device according to the present invention, the first medium, the second medium, and the third medium are laminated in that order. The electrodes are disposed at the interface between the first and second media. The sound velocity in the second medium and/or the material of the second medium is different from that of the third medium. The energy of the boundary wave is distributed as shown in Fig. 5. Thus, changing the thickness of the second medium can adjust the sound velocity with which the boundary wave propagates therethrough. Changing the thickness of the third medium cannot adjust the sound velocity with which the boundary wave propagates therethrough because the energy of the boundary wave is not distributed on the surface of the third medium. An operating frequency F of the boundary wave device is expressed as $F = V/\lambda$, where V represents the sound velocity of a boundary wave; and λ represents the period of IDT strips. Thus, adjusting the sound velocity can regulate the operating frequency of the boundary wave device.

[0034] In the third aspect of the present invention, the first medium, the second medium, the third medium, and the fourth medium are laminated in that order. The electrodes are disposed at the interface between the first and second media. The sound velocity in the third medium and/or the material of the third medium is different from that of the fourth medium. The energy of the boundary wave is distributed as shown in Fig. 6. Thus, changing the thickness of the third medium can adjust the sound velocity with which the boundary wave propagates therethrough. Changing the thickness of the fourth medium cannot adjust the sound velocity with which the boundary wave propagates therethrough because the energy of the boundary wave is not distributed on the surface of the fourth medium. An operating frequency F of the boundary wave device is expressed as $F = V/\lambda$, where V represents the sound velocity of a boundary wave; and λ represents the period of IDT strips. Thus, adjusting the sound velocity can regulate the operating frequency of the boundary wave device.

[0035] In the third aspect of the present invention, the second and fourth media may be composed of the same material, thereby improving various characteristics. In general, many dielectric materials and metal materials have negative temperature coefficients of sound velocities of acoustic waves. When the first to third media and the electrode layer are each composed of a material having a negative temperature coefficient, the boundary acoustic wave has a negative temperature coefficient. The temperature coefficient of operating frequency of a boundary acoustic wave device, i.e., TCF, is expressed as:

$$TCF = \frac{1}{V} \cdot \frac{\Delta V}{\Delta T} - \alpha$$

where V represents the sound velocity of a boundary wave; ΔV represents the width of variation in sound velocity; ΔT represents the width of variation in temperature; and α represents a coefficient of linear thermal expansion. Many dielectric materials and metal materials have positive coefficients of linear thermal expansion. Thus, the boundary acoustic wave device has a negative TCF. In the boundary acoustic wave device, the TCF is preferably zero.

[0036] To improve the temperature characteristics, the second and fourth media may be each composed of SiO_2

having a positive temperature coefficient. In this case, it is possible to bring the temperature coefficient closer to zero compared with the case in which the second medium is composed of a dielectric material having a negative temperature coefficient. Furthermore, the appropriate selection of the materials of the first and third media and the thickness of each media can bring the TCF to zero.

Brief Description of the Drawings

[0037]

Fig. 1 is a schematic front cross-sectional view illustrating a boundary acoustic wave device according to an embodiment of the present invention.

Fig. 2(a) is a plan view showing an electrode structure of a boundary acoustic wave device according to the present invention, and Fig. 2(b) is a front cross-sectional view of the boundary acoustic wave device.

Fig. 3 is a schematic fragmentary enlarged cross-sectional view illustrating duty ratios of the IDT and reflectors of a boundary acoustic wave device.

Fig. 4 shows the relationship between the cross-sectional structure of a known boundary acoustic wave device and the energy distribution of a boundary acoustic wave.

Fig. 5 shows the relationship between a cross-sectional structure of a boundary acoustic wave device according to a first aspect of the present invention and the energy distribution of a boundary acoustic wave.

Fig. 6 shows the relationship between a cross-sectional structure of a boundary acoustic wave device according to a second aspect of the present invention and the energy distribution of a boundary acoustic wave.

Fig. 7 is a graph showing the relationship between the thickness H2 of a SiO₂ film, which is a second medium of a boundary acoustic wave device in Example 1, and the sound velocity (center frequency $\times \lambda$).

Fig. 8 is a graph showing the relationship between the thickness H2 of a SiO₂ film, which is a second medium of a boundary acoustic wave device in Example 1, and the temperature coefficient of frequency.

Fig. 9 is a graph showing the relationship between the thickness H3 of a polycrystalline Si film, which is a third medium of a boundary acoustic wave device in Example 2, and the sound velocity (center frequency $\times \lambda$).

Fig. 10 is a graph showing the relationship between the thickness H3 of a polycrystalline Si film, which is a third medium of a boundary acoustic wave device in Example 2, and the temperature coefficient of frequency.

Fig. 11 is a circuit diagram of a ladder filter as an example of a boundary acoustic wave device according to the present invention.

Fig. 12 is a perspective view illustrating an example of a known boundary acoustic wave device.

Fig. 13 is a graph showing frequency characteristics of the known boundary acoustic wave device and shows production tolerance in frequency.

Reference Numerals

[0038]

- 1 first medium
- 2 second medium
- 3 third medium
- 5 electrode
- 20 boundary acoustic wave device
- 21 first medium
- 22 second medium
- 23 third medium
- 24 fourth medium
- 25 electrode

Best Mode for Carrying Out the Invention

[0039] The present invention will be explained by describing specific embodiments according to the present invention with reference to the drawings.

[0040] The inventors have produced a boundary acoustic wave device shown in Figs. 2(a) and 2(b) and studied the device. Fig. 2(b) is a front cross-sectional view of the boundary acoustic wave device 200. The boundary acoustic wave device 200 has a laminated structure of a first medium 201 and a second medium 202. An input IDT 205, output IDTs 206 and 207, which function as electrodes, and reflectors 208 and 209 are disposed at the interface between the first

and second media 201 and 202. Fig. 2(a) is a plan view showing the electrode structure.

[0041] In the boundary acoustic wave device 200, the first medium 201 was a 15° rotated Y-cut X-propagating LiNbO₃ substrate. A wavelength λ based on the center-to-center distance of the IDTs 205 to 207 was 3.0 μm . The cross length of electrode fingers was 50 λ . The input IDT 205 had 14.5 pairs of electrode fingers. The period of arrangement of the four outer electrode fingers of the IDT 205 in the propagation direction of a boundary wave was 0.86 λ . The output IDTs 206 and 207 each had 8.5 pairs of electrode fingers, the period of arrangement of four electrode fingers adjacent to the input IDT 205 being 0.86 λ . The reflectors 208 and 209 each had 41 electrode fingers and a period of arrangement of 1.033 λ . Pass-band regions of the filter were disposed in reflection-band regions of the reflectors 208 and 209. The center-to-center distances of the nearest-neighbor electrodes between the input IDT 205 and each of the output IDTs 206 and 207 was 0.43 λ . The center-to-center distance of the nearest-neighbor electrodes between the output IDT 206 and the reflector 208 and between the output IDT 207 and the reflector 209 was 0.5 λ . The IDTs 205 to 207 and the reflectors 208 and 209 each had a duty ratio of 0.5.

[0042] Fig. 3 is a schematic cross-sectional view illustrating the duty ratio. The term "duty ratio" means a value expressed as L/P in Fig. 3, where L represents the width of an electrode finger; and P represents the center-to-center distance of the spaces between adjacent electrode fingers in the propagation direction of the boundary wave. The period of arrangement of the IDT and the reflector, i.e., λ , is expressed as $\lambda = 2 \times P$.

[0043] The above-described electrodes were each formed of a laminate including an underlying NiCr film having a thickness of 0.003 λ and a Au film having a thickness of 0.05 λ disposed on the underlying NiCr film. The second medium was formed of a SiO₂ film.

[0044] Two boundary acoustic wave devices described above were produced. That is, a first lot and a second lot of the boundary acoustic wave devices were obtained.

[0045] S21 characteristics (transmission characteristics) of the boundary acoustic wave devices of the first and second lots were measured. As shown in Fig. 13, the results demonstrated that the mean center frequency of the pass band of the first lot was different from that of the second lot by 5.6 MHz.

[0046] The center frequency of the pass band of the filter needs to be matched to a target center frequency. Variation in the frequency of the pass band needs to be suppressed with high precision. A first lot and a second lot of the boundary acoustic wave devices were produced again in the same way as the first and second lots. The pass frequencies were measured before and after the formation of the SiO₂ films as the second media. Table 1 shows the results.

Table 1

	First lot	Second lot
Before formation of SiO ₂ film	844 MHz	847 MHz
After formation of SiO ₂ film	1,060 MHz	1,065 MHz

[0047] As is apparent from Table 1, the width of variation in frequency was as large as about 220 MHz before and after the formation of the SiO₂ film in each of the first and second lots. Comparison of a result of the boundary acoustic wave device of the first lot with that of the second lot showed that the frequency difference was further increased by 2 MHz after the formation of the SiO₂ film. Thus, the results demonstrate that production tolerance of the SiO₂ film, which is the second medium, significantly affects variation in the frequency of the final boundary acoustic wave device.

[0048] In the case of the formation of the SiO₂ film functioning as the second medium after the formation of the electrodes on the first medium as described above, the occurrence of variation in the second medium causes significant variation in the frequency of the boundary acoustic wave device.

[0049] In contrast, according to the first aspect of the present invention, the frequency adjustment is performed after the formation of a second medium of a laminate. Thus, production tolerance in frequency is significantly reduced after the step of adjusting the frequency. In the case in which a third medium is further formed, even when variation in the third medium occurs, variation in the frequency of the resulting boundary acoustic wave device is effectively suppressed. This will be explained with reference to Figs. 1, 4, and 5.

[0050] Fig. 1 is a partially cutout front cross-sectional view of a boundary acoustic wave device according to an embodiment of the present invention. In this boundary acoustic wave device, a second medium 2 and a third medium 3 are laminated on a first medium 1. Electrodes 5 are disposed at the interface between the first medium 1 and the second medium 2. In this embodiment, after the formation of the electrodes 5 on the first medium, the second medium 2 is formed, thus producing a laminate. After the step of forming the laminate, the frequency adjustment is performed. More specifically, the frequency is adjusted by changing the thickness of the second medium 2. Examples of a method of changing the thickness of the second medium 2 include a method in which the second medium 2 is processed by etching or the like to reduce the thickness; and a method in which a film composed of a material identical to that of the second medium is formed by a film-forming process such as sputtering to substantially increase the thickness of the

second medium 2. Alternatively, the thickness of the second medium 2 may be adjusted in the step of forming the second medium 2.

[0051] In this embodiment, after the thickness adjustment, the third medium 3 is formed.

[0052] Methods for producing the second medium 2 and the third medium 3 are not limited to film-forming methods such as sputtering. Various methods may be employed. With respect to the third medium 3, a separately prepared film or a plate formed of the third medium may be bonded on the second medium 2.

[0053] In the boundary acoustic wave device according to the first aspect of the present invention, the third medium 3 needs to be different from the second medium 2 in terms of the sound velocity with which a boundary wave propagates therethrough and/or in terms of material. In the case where the sound velocity in the second medium 2 is identical to that of the third medium 3, and where the material of the second medium 2 is identical to that of the third medium 3, even when the above-described step of adjusting the frequency is performed, the frequency is not changed, in some cases.

[0054] Fig. 4 shows the relationship between a schematic front cross-sectional view of a known boundary acoustic wave device and the energy distribution of a boundary acoustic wave. As is apparent from Fig. 4, in the boundary acoustic wave device 200, electrodes such as the input IDT 205 are disposed between the first medium 201 having a thickness of H1 and the second medium 202 having a thickness of H2. As shown at the right-hand side of Fig. 4, the energy of the boundary wave is concentrated on and around the interface. In the first and second media 201 and 202, the energy decreases with distance from the interface. However, for example, in the second medium 202, the energy is also present also in the hatched portion in Fig. 4. Thus, the occurrence of the variation in the second medium after the formation of the second medium 202 results in variation in frequency.

[0055] Fig. 5 shows the relationship between a schematic cross-sectional view of the boundary acoustic wave device of the above-described embodiment according to the first aspect of the present invention and the energy distribution of a boundary acoustic wave.

[0056] In the boundary acoustic wave device shown in Fig. 5, the electrodes 5 are disposed at the interface between the first medium 1 having a thickness of H1 and the second medium 2 having a thickness of H2. In this case, the electrodes 5 are formed on the first medium 1. Then, the second medium 2 is formed. After the step of forming the second medium 2, the frequency adjustment is performed. After the frequency adjustment, the third medium 3 having a thickness of H3 is formed. In the resulting boundary acoustic wave device, after the step of forming the laminate having the first medium 1 and the second medium 2, the frequency adjustment is performed.

[0057] With respect to the energy distribution of the boundary wave in the boundary acoustic wave device, only part of energy is distributed in the third medium 3 as shown at the right-hand side of Fig. 5. Thus, even when variation in the third medium 3 from production tolerance occurs, nonuniformity in frequency due to the variation is very small. Therefore, the frequency adjustment before the formation of the third medium 3 can significantly reduce variation in the frequency of the boundary acoustic wave device after the formation of the third medium 3.

[0058] Fig. 6 shows the relationship between a schematic cross-sectional view illustrating the reason for the small variation in the frequency of a boundary acoustic wave device according to the second aspect of the present invention and the energy distribution of a boundary acoustic wave.

[0059] In a boundary acoustic wave device 20 according to the second aspect of the present invention, electrodes 25 are disposed between a first medium 21 having a thickness of H1 and a second medium 22 having a thickness of H2. A third medium 23 having a thickness of H3 is laminated thereon to form a laminate. After step of forming the laminate, the frequency adjustment is performed. A fourth medium 24 having a thickness of H4 is laminated on the third medium 23. In the resulting boundary acoustic wave device 20, the energy distribution of a boundary wave is shown at the right-hand side of Fig. 6. That is, only part of the energy is distributed in the fourth medium. Thus, in the case where after the step of forming the laminate having the third medium 23, the frequency adjustment is performed to significantly reduce variation in frequency, even when the fourth medium 24 is further formed thereon, it is possible to suppress variation in frequency.

[0060] In the second aspect of the present invention, the third medium 23 needs to be different from the fourth medium 24 in terms of the sound velocity with which a boundary wave propagates therethrough and/or in terms of material, otherwise the frequency is not changed.

[0061] As described above, variation in frequency can be suppressed in the production process according to the first and second aspects of the present invention because the frequency adjustment is performed before the third or fourth medium formed at the end, and then the third or fourth medium is formed. That is, only part of the energy of a boundary wave is distributed in the third medium according to the first aspect of the present invention and the fourth medium according to the second aspect of the present invention. Thus, even when production tolerance in the third medium according to the first aspect of the present invention and production tolerance in the fourth medium according to the second aspect of the present invention occur, these production tolerance have less effect on variation in the frequency of a final boundary acoustic wave device. Therefore, it is possible to provide a boundary acoustic wave device having only small variation in frequency by performing the frequency adjustment after the step of forming the laminate.

[0062] In the second aspect of the present invention, the second medium 22 may be composed of a material identical

to that of the fourth medium 24 or may be composed of a material different from that of the fourth medium 24. For example, in the case where the second medium 22 is composed of SiO_2 , which has a positive temperature coefficient of frequency, combining SiO_2 with various materials each having a negative temperature coefficient of frequency can improve the temperature coefficient of frequency of the boundary wave device. In the first aspect of the present invention, when one of the second medium 2 and the third medium 3 is composed of SiO_2 , the other is preferably composed of a material having a negative temperature coefficient of frequency other than SiO_2 . Both second and third media 2 and 3 may be composed of SiO_2 . In this case, it is necessary that SiO_2 media having different densities, hardness (elastic constant), and the like be used to provide different sound velocities. Thus, the effect of improving the temperature coefficient of frequency may be degraded. Therefore, in the first aspect of the present invention, either of the second medium 2 and the third medium 3 is preferably composed of SiO_2 .

[0063] In the second aspect of the present invention, when the second medium 22 and the fourth medium 24 are each composed of SiO_2 , the third medium 23 may be composed of a material other than SiO_2 . Thus, it is possible to perform the frequency adjustment while maintaining the effect of improving the temperature coefficient of frequency.

[0064] In the first aspect of the present invention, the thickness H_2 (λ) of the second medium is preferably 1λ or less. When the second medium has a thickness of 1λ or less, the energy of a boundary acoustic wave is negligibly distributed in the third medium; hence, it is possible to effectively reduce variation in frequency due to production tolerance in the third medium. Furthermore, the thickness H_3 of the third medium preferably exceeds 0.5λ . At a thickness of the third medium exceeding 0.5λ , as shown in Fig. 5, even when the energy of a boundary wave is distributed in the third medium, the energy of the boundary wave is surely reduced until the boundary wave reaches one surface of the third medium 3 opposite the other surface being in contact with the second medium 2, thereby resulting in satisfactory boundary wave propagation. In such a structure, even when foreign matter is attached on the surface, the characteristics of the boundary wave device are stable.

[0065] In the second aspect of the present invention, at a thickness H_2 of the second medium of 0.5λ or less, as shown in Fig. 6, the energy of a boundary wave is also distributed in the third medium. Furthermore, at a thickness H_3 of the third medium of 0.1λ or less, the energy of the boundary wave is also distributed in the fourth medium. The sound velocity in the third medium is different from those in the second and fourth media. Thus, adjusting the thickness of the third medium can regulate the sound velocity with which a boundary wave propagates therethrough. When the energy of a boundary wave is not distributed in the third medium because the second medium has a large thickness, the sound velocity with which the boundary wave propagates therethrough cannot be regulated by changing the state of the third medium. When the energy of the boundary wave is not distributed in the fourth medium because the third medium has a large thickness, the sound velocity with which the boundary wave propagates therethrough cannot be regulated by changing the thickness of the fourth medium.

[0066] As shown in Fig. 6, the energy of the boundary wave is surely reduced until the boundary wave reaches the surface of the medium 4 opposite the surface being in contact with the medium 3, thereby resulting in satisfactory boundary wave propagation. In such a structure, even when foreign matter is attached on the surface, the characteristics of the boundary wave device are stable.

[0067] Specific examples will be described below.

(EXAMPLE 1)

[0068] A 15° rotated Y-cut X-propagating LiNbO_3 substrate was prepared as a first medium. The electrode structure shown in Fig. 2 was formed on the LiNbO_3 substrate. That is, the input IDT 205, the output IDTs 206 and 207, and the reflectors 208 and 209 shown in Fig. 2(a) were formed. The electrodes were made by the following procedure: after washing the LiNbO_3 substrate, a resist was spin-coated thereon, prebaked, and developed to form a resist pattern. A NiCr film and then a Au film were formed in that order by vacuum evaporation. The resist was lifted-off. The resulting electrodes were washed. Thereby, the electrode structure including the Au film having a thickness of 0.055λ and the NiCr film having a thickness of 0.001λ was obtained.

[0069] Next, a SiO_2 film functioning as a second medium and having a thickness of 0.1λ was formed over the surface having the electrodes of the LiNbO_3 substrate by RF sputtering, thereby producing a laminate shown in Fig. 2(b).

[0070] A resist was spin-coated on the SiO_2 film and then developed to form a resist pattern. Reactive ion etching and the removal of the resist were performed to remove the SiO_2 film disposed on the electrodes to be electrically connected with the exterior.

[0071] The resulting exposed external terminals were brought into contact with probes of a wafer prober to measure a center frequency. The SiO_2 film was processed in such a manner that the resulting measurement corresponds to a target center frequency. In this step, the SiO_2 film was processed by a method in which the SiO_2 film was etched by reactive ion etching to reduce the thickness or a method in which a SiO_2 film was formed by sputtering to increase the thickness.

[0072] That is, when the measurement was lower than the target center frequency, the thickness of the SiO_2 film was

reduced as described above. In contrast, when the measurement was higher than the target center frequency, the thickness of the SiO₂ film was increased.

[0073] At this point, a propagating boundary wave was not a boundary acoustic wave but a surface acoustic wave, in which displacement was concentrated on the surface. The frequency adjustment was performed for the surface acoustic wave.

[0074] After the frequency adjustment, a polycrystalline Si film having a thickness of 1 λ was formed as a third medium by sputtering on the SiO₂ film.

[0075] At this point, a propagating boundary wave was a boundary acoustic wave.

[0076] A resist was spin-coated on the polycrystalline Si film, developed, baked, and patterned by reactive ion etching. The resist was removed, and then polycrystalline Si deposited on the external terminals was removed. Thereby, many boundary acoustic wave devices were produced.

[0077] The resulting boundary acoustic wave devices have a small variation in resonant frequency.

[0078] Fig. 7 is a graph showing the relationship between the thickness H2 of the SiO₂ film of the boundary acoustic wave device produced in this example and the sound velocity, which is determined by multiplying the center frequency by λ , in the boundary wave device. Fig. 8 is a graph showing the relationship between the thickness H2 of the SiO₂ film and the temperature coefficient of frequency (TCF)(ppm/°C). The thickness of the polycrystalline Si film functioning as the third medium is unrelated to the sound velocity because of the boundary acoustic wave device.

[0079] Fig. 7 clearly shows that the sound velocity decreases as the thickness of the SiO₂ film functioning as the second medium is increased. Fig. 8 clearly shows that the temperature coefficient of frequency (TCF) is improved as the thickness H2 of the SiO₂ film.

(EXAMPLE 2)

[0080] A 15° rotated Y-cut X-propagating LiNbO₃ substrate was prepared as a first medium. The electrode structure shown in Fig. 2(a) was formed as in EXAMPLE 1. Many LiNbO₃ substrates each having the electrodes were prepared.

[0081] A SiO₂ film was formed over the electrodes disposed on the LiNbO₃ substrate by RF sputtering. In this case, structures having the SiO₂ films with thicknesses of 0.1 λ , 0.3 λ , 0.5 λ , and 1.0 λ were produced. Then, a polycrystalline Si film having a thickness of 0.5 λ was formed on each SiO₂ film by RF sputtering. Thereby, a laminate having a laminated structure of poly-Si/SiO₂/electrodes/LiNbO₃ substrate, i.e., the laminate of third medium/second medium/electrodes/first medium was prepared.

[0082] At this point, a propagating boundary wave was not a boundary acoustic wave but a surface acoustic wave, in which displacement was concentrated on the surface. The frequency adjustment was performed for the surface acoustic wave.

[0083] A resist was spin-coated on the resulting polycrystalline Si film of the laminate, prebaked, and patterned. Reactive ion etching and the removal of the resist were performed to remove polycrystalline Si and SiO₂ disposed on external terminals, thereby exposing the external terminals. The exposed external terminals were brought into contact with probes of a wafer prober to measure a center frequency.

[0084] The polycrystalline Si was processed in such a manner that the resulting measurement corresponds to a target center frequency. In this step, when the measurement was lower than the target center frequency, the polycrystalline Si was processed to reduce the thickness by reactive ion etching. In contrast, when the measurement was higher than the target center frequency, polycrystalline Si film was formed again by sputtering to increase the thickness of the polycrystalline Si film. After the frequency adjustment, a SiO₂ film having a thickness of 1 λ formed as a fourth medium by sputtering on the polycrystalline Si.

[0085] At this point, a propagating boundary wave was a boundary acoustic wave.

[0086] A resist was spin-coated on the SiO₂ film and patterned. Reactive ion etching and the removal of the resist were performed to remove the SiO₂ film disposed on the external electrodes. In this way, many boundary acoustic wave devices were produced.

[0087] The center frequencies of the resulting many boundary acoustic wave devices were measured. Variations in center frequencies of the boundary acoustic wave devices including the second media having thicknesses of 0.1 λ , 0.3 λ , 0.5 λ , and 1.0 λ decrease with increasing thickness.

[0088] Fig. 9 is a graph showing the relationship between the thickness H3 of polycrystalline Si film, functioning as a third medium, of each of the boundary acoustic wave devices having the SiO₂ films, functioning as the second media, with thicknesses H2 of 0.1 λ , 0.3 λ , and 0.5 λ and the sound velocity (center frequency $\times \lambda$). Fig. 10 is a graph showing the relationship between the thickness H3 of a polycrystalline Si film and the temperature coefficient of frequency.

[0089] The thickness of the SiO₂ film functioning as the fourth medium is unrelated to the sound velocity because of the boundary acoustic wave device.

[0090] Fig. 9 clearly shows that the sound velocity is significantly changed within the range of 0 to 0.1 λ in thickness of the polycrystalline Si film, and the frequency adjustment can be efficiently performed within the range. Fig. 10 clearly

shows that the temperature coefficient of frequency (TCF) is improved up to 25 ppm/°C within the range compared with the temperature coefficient of frequency in EXAMPLE 1 shown in Fig. 8. At a thickness of the SiO₂ film, functioning as the second medium, of 0.5λ , the sound velocity was changed as shown in Fig. 9. At a thickness of the second medium exceeding 0.5λ , the sound velocity was not changed by changing the thickness H3 of the polycrystalline Si film.

[0091] Thus, in the boundary acoustic wave device including the first to fourth media laminated, the thickness H2 of the second medium is preferably 0.5λ .

[0092] In the examples described above, the longitudinally coupled boundary acoustic wave resonator filter having a three-IDT structure shown in Fig. 2(a) has been described. However, the boundary acoustic wave devices according to the present invention may have various electrode structures. That is, a longitudinally coupled boundary acoustic wave resonator filter including two or more IDTs may be used. As shown in Fig. 11, which is a circuit diagram, a ladder filter in which a plurality of boundary acoustic wave resonators S1, S2, P1, and P2 are connected may be used. While four boundary acoustic wave resonators are connected in Fig. 11, a ladder filter including a desired number of stages may be used.

[0093] The number of resonators in the ladder filter is not particularly limited. In the boundary acoustic wave device and the process for producing the boundary acoustic wave device according to the present invention may provide, a laterally coupled boundary acoustic wave filter may be used.

[0094] A comb-shape transducer (see "Dansei Hyomenha Kogaku", published by Institute of Electronics, Information and Communication Engineers, sixth impression of the first edition, page 57) may be used as the electrode, in place of the IDT. When such a comb-shape transducer is used, λ is defined as the period of arrangement of strips of the comb-shape transducer. That is, a wavelength at which an electroacoustic transducer is excited may be defined as λ .

[0095] In EXAMPLES 1 and 2, the electrode is formed of the laminate including the Au electrode layer as a main component and the underlying NiCr layer. However, the electrode may be composed of other metals. For example, the electrode may be composed of one metal selected from Ag, Cu, Fe, Ta, W, Ti, and Pt. In addition, to enhance adhesion between the electrode and the first and second media and to enhance power durability, a second thin electrode layer composed of Ti, Cr, NiCr, or the like may be laminated. The second electrode layer may be disposed between the first medium and the electrode layer mainly composed of Au or the like. Alternatively, the second electrode layer may be disposed between the main electrode layer and the second medium. Furthermore, the electrode may have a structure in which three or more electrode layers are laminated. In this case, the second electrode layer may be laminated as an interlayer.

[0096] In the present invention, the electrode structure may be composed of an alloy of a plurality of metals.

[0097] The materials constituting the first to third media and the first to fourth media according to the present invention are not particularly limited. That is, various dielectrics may be used as the media. An example thereof is one material selected from the group consisting of lithium niobate, potassium niobate, lithium tantalate, lithium tetraborate, langasite, langanite, quartz, lead zirconate titanate ceramics, ZnO, AlN, silicon oxides, glass, silicon, sapphire, silicon nitrides, and carbon nitrides.

[0098] Furthermore, the medium is not necessarily composed of a single material but may have a laminated structure in which a plurality of medium layers are laminated. That is, at least one medium among the first to third media and the first to fourth media may have the laminated structure in which a plurality of medium layers are laminated.

[0099] Furthermore, in the boundary acoustic wave device according to the present invention, a protective layer for enhancing strength and preventing the penetration of corrosive gas and the like may be formed at the outer side. Although, the boundary acoustic wave device may be housed in a package if increased size of the component does not cause problems.

[0100] The protective layer may be composed of an insulating material, such as titanium oxide, aluminum nitride, or aluminum oxide; a metal, such as Au, Al, or W; or a resin such as an epoxy resin.

Claims

1. A process for producing a boundary acoustic wave device that includes a first medium, a second medium, and a third medium laminated in that order; and electrodes disposed at the interface between the first medium and the second medium, the process comprising the steps of:

preparing a laminate including the first medium, the second medium, and the electrodes disposed at the interface between the first medium and the second medium;

adjusting the thickness of the second medium, after the step of preparing the laminate, to regulate a frequency or the sound velocity of a surface acoustic wave, a pseudo-boundary acoustic wave, or a boundary acoustic wave; and

after the adjusting step, forming the third medium different from the second medium in terms of the sound

velocity with which the boundary acoustic wave propagates therethrough and/or in terms of material.

2. The process for producing a boundary acoustic wave device according to claim 1, wherein the third medium has a thickness exceeding 0.5λ , wherein λ represents the wavelength of the boundary acoustic wave.

3. A process for producing a boundary acoustic wave device that includes a first medium, a second medium, a third medium, and a fourth medium laminated in that order; and electrodes disposed at the interface between the first medium and the second medium, the process comprising the steps of:

preparing a laminate including the first medium, the second medium, and the third medium formed in that order and electrodes disposed at the interface between the first medium and the second medium;
adjusting a frequency or the sound velocity of a surface acoustic wave, a pseudo-boundary acoustic wave, or a boundary acoustic wave after the step of preparing the laminate; and
after the adjusting step, forming the fourth medium, the sound velocity in the fourth medium and/or the material of the fourth medium being different from that of the third medium.

4. The process for producing a boundary acoustic wave device according to claim 3, wherein the fourth medium has a thickness exceeding 0.5λ , wherein λ represents the wavelength of the boundary acoustic wave.

5. The process for producing a boundary acoustic wave device according to any one of claims 1 to 4, wherein at least one medium has a laminated structure in which a plurality of material layers are laminated.

6. The process for producing a boundary acoustic wave device according to any one of claims 1 to 5, wherein the electrodes are each composed of one metal selected from the group consisting of Au, Ag, Cu, Fe, Ta, W, Ti, and Pt.

7. The process for producing a boundary acoustic wave device according to any one of claims 1 to 6, wherein the medium layers are each composed of at least one material selected from the group consisting of lithium niobate, potassium niobate, lithium tantalate, lithium tetraborate, langasite, langanite, quartz, lead zirconate titanate ceramics, ZnO, AlN, silicon oxides, glass, silicon, sapphire, silicon nitrides, and carbon nitrides.

8. The process for producing a boundary acoustic wave device according to any one of claims 1 to 7, wherein the electrodes constitute a boundary acoustic wave resonator or a boundary acoustic wave filter, and the boundary acoustic wave device is the boundary acoustic wave resonator or the boundary acoustic wave filter.

9. A boundary acoustic wave device comprising a first medium, a second medium, a third medium, and a fourth medium laminated in that order; and electrodes disposed at the interface between the first medium and the second medium, the sound velocity in the third medium and/or the material of the third medium being different from that of the fourth medium.

FIG.1

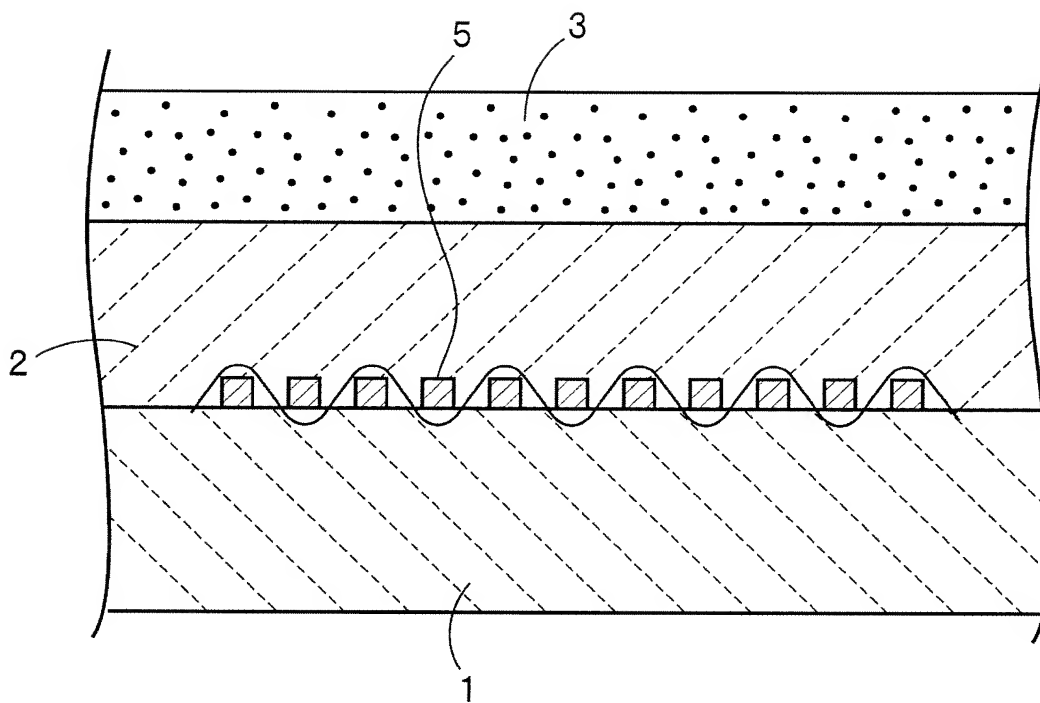


FIG.2

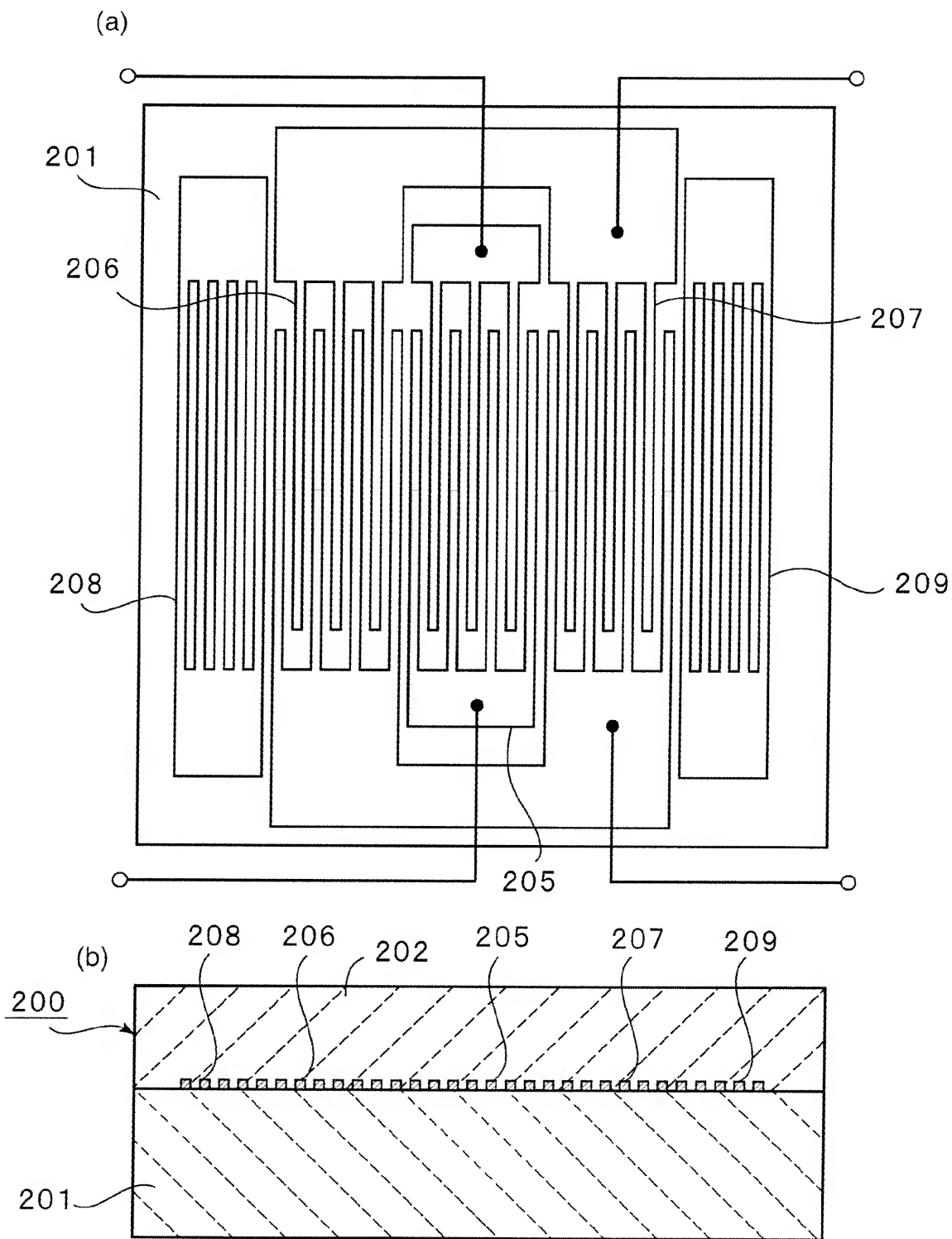


FIG.3

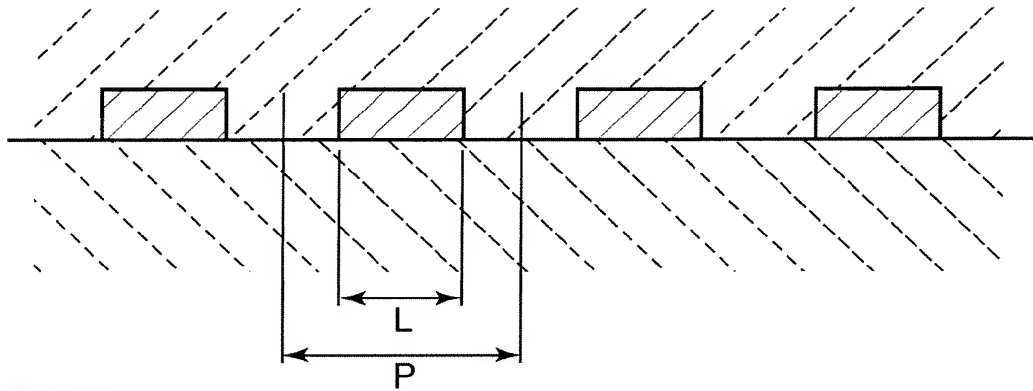


FIG.4

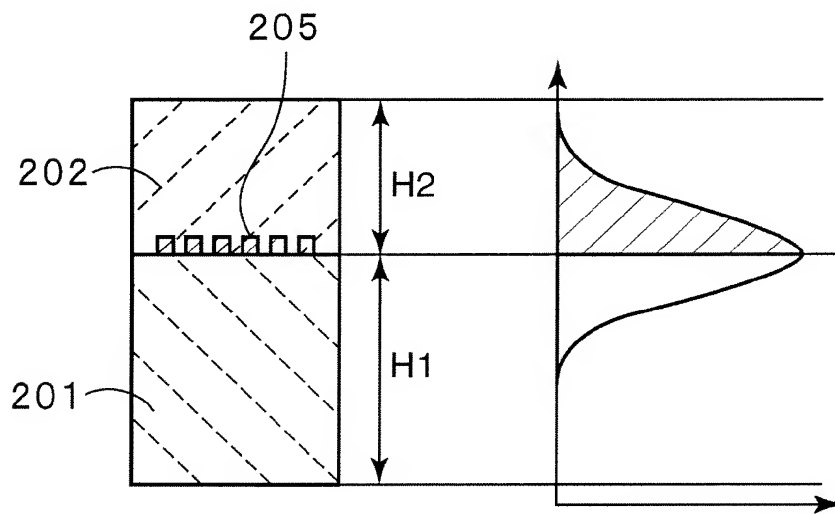


FIG.5

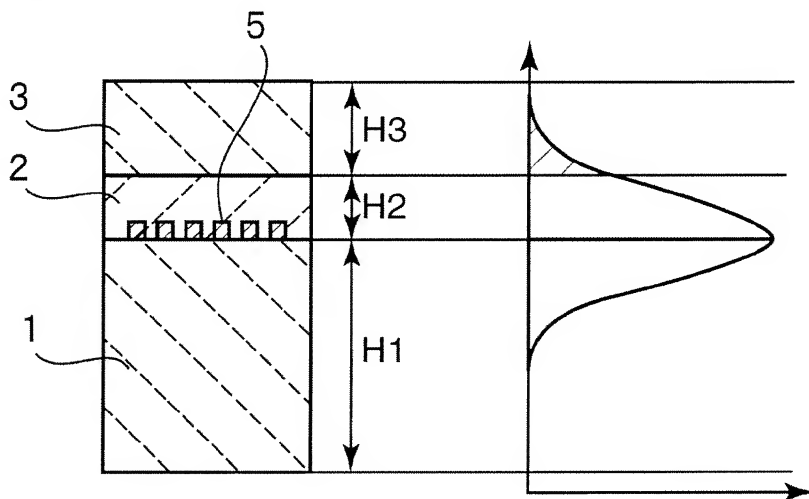


FIG. 6

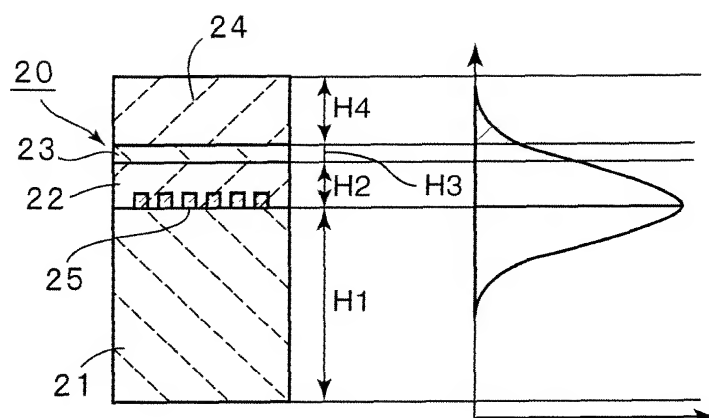


FIG. 7

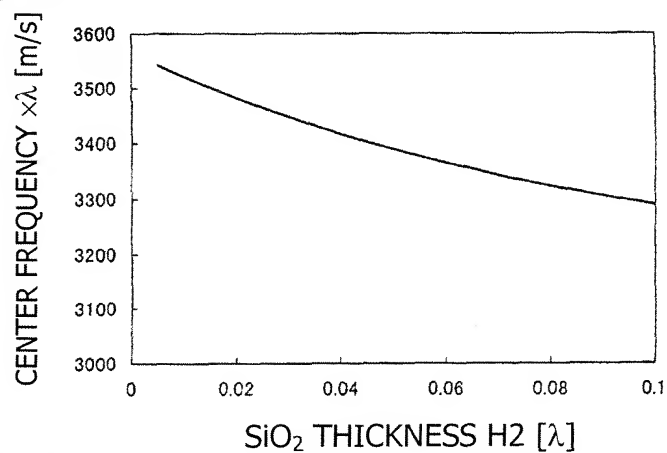


FIG. 8

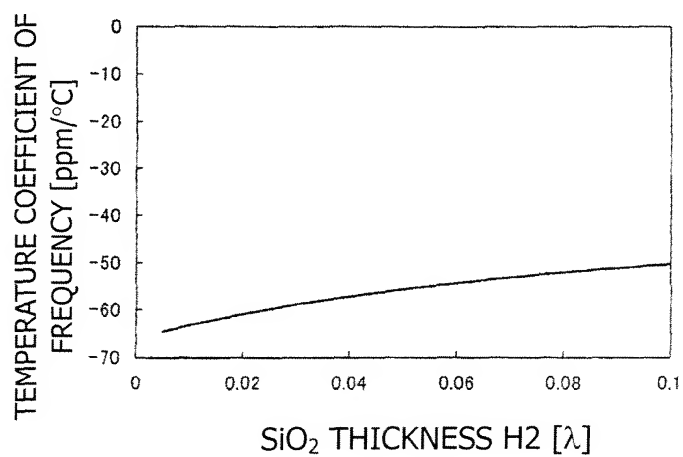


FIG.9

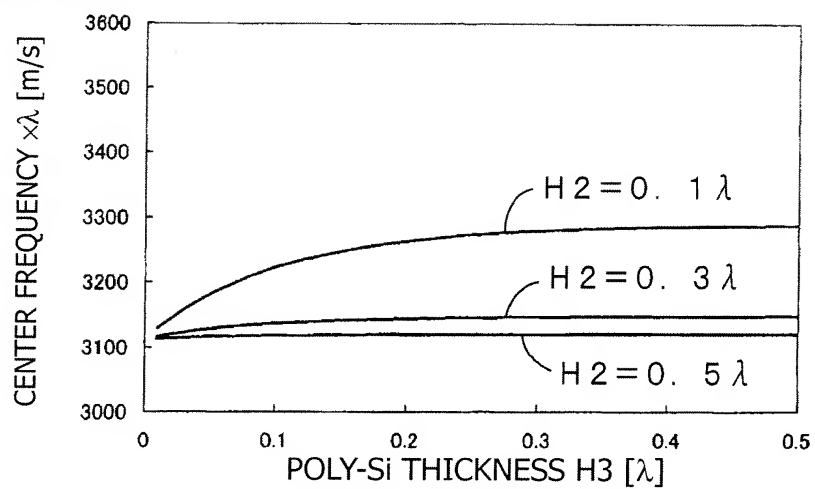


FIG.10

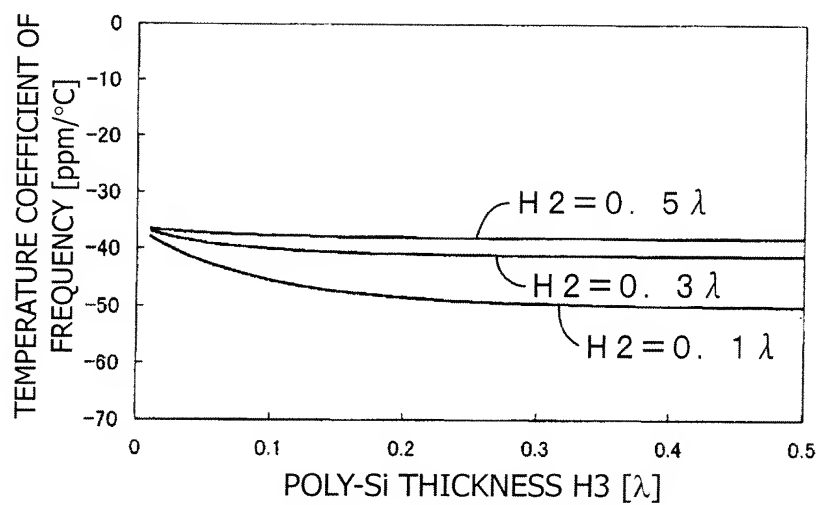


FIG.11

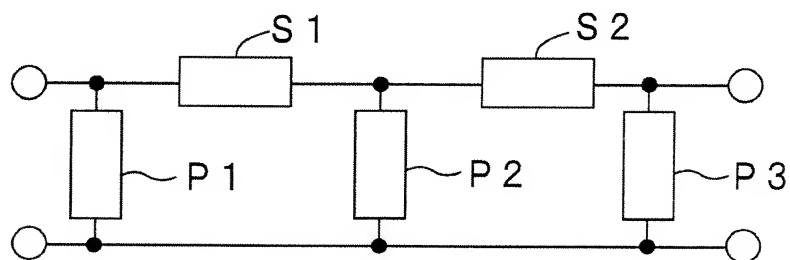


FIG.12

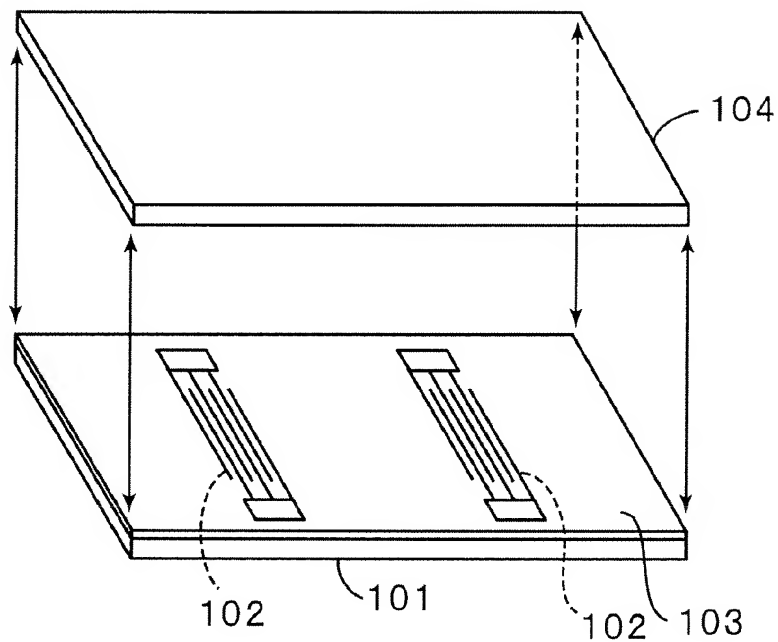
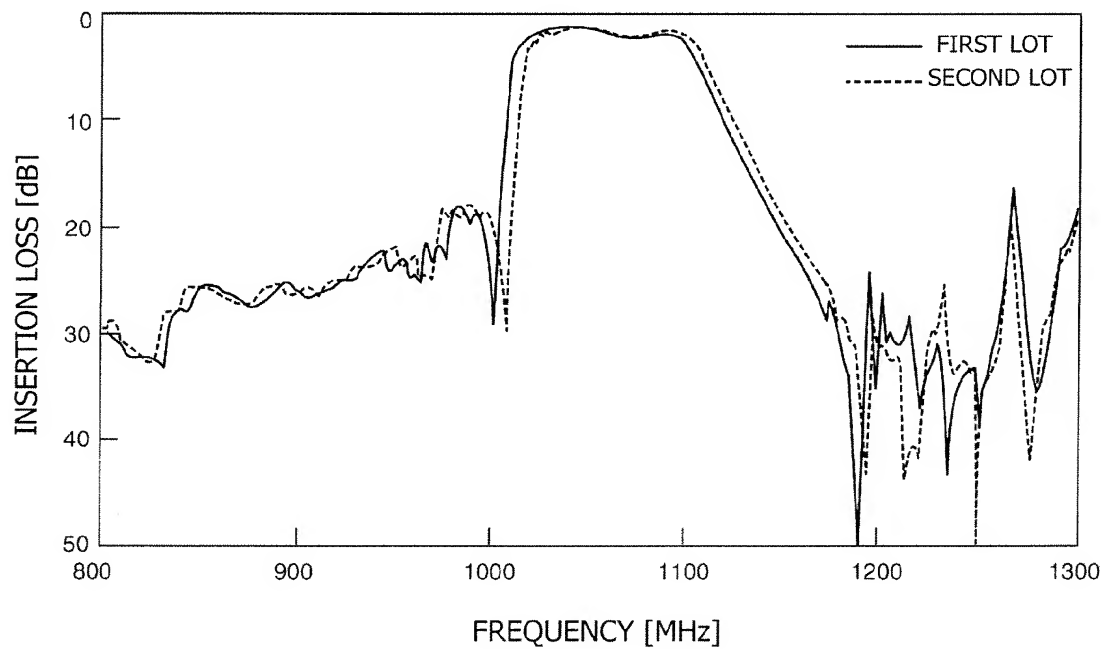


FIG.13



INTERNATIONAL SEARCH REPORT

International application No.

PCT/JP2005/005414

A. CLASSIFICATION OF SUBJECT MATTER Int. Cl. ⁷ H03H3/08, 9/145		
According to International Patent Classification (IPC) or to both national classification and IPC		
B. FIELDS SEARCHED Minimum documentation searched (classification system followed by classification symbols) Int. Cl. ⁷ H03H3/08-3/10, 9/145, 9/25, 9/42-9/44, 9/64, 9/68, 9/72, 9/76		
Documentation searched other than minimum documentation to the extent that such documents are included in the fields searched Jitsuyo Shinan Koho 1922-1996 Jitsuyo Shinan Toroku Koho 1996-2005 Kokai Jitsuyo Shinan Koho 1971-2005 Toroku Jitsuyo Shinan Koho 1994-2005		
Electronic data base consulted during the international search (name of data base and, where practicable, search terms used)		
C. DOCUMENTS CONSIDERED TO BE RELEVANT		
Category*	Citation of document, with indication, where appropriate, of the relevant passages	Relevant to claim No.
Y A	JP 7-212174 A (Hitachi, Ltd.), 11 August, 1995 (11.08.95), Claims 1 to 2; Par. Nos. [0006] to [0019]; Figs. 1, 5 (Family: none)	1-2, 5-8 3-4
X Y A	WO 1998/52279 A1 (Hitachi, Ltd.), 19 November, 1998 (19.11.98), Claims 1, 15, 17; pages 9 to 13; Figs. 5, 11, 12 (Family: none)	9 1-2, 5-8 3-4
<input checked="" type="checkbox"/> Further documents are listed in the continuation of Box C. <input type="checkbox"/> See patent family annex.		
* Special categories of cited documents: "A" document defining the general state of the art which is not considered to be of particular relevance "E" earlier application or patent but published on or after the international filing date "L" document which may throw doubts on priority claim(s) or which is cited to establish the publication date of another citation or other special reason (as specified) "O" document referring to an oral disclosure, use, exhibition or other means "P" document published prior to the international filing date but later than the priority date claimed "T" later document published after the international filing date or priority date and not in conflict with the application but cited to understand the principle or theory underlying the invention "X" document of particular relevance; the claimed invention cannot be considered novel or cannot be considered to involve an inventive step when the document is taken alone "Y" document of particular relevance; the claimed invention cannot be considered to involve an inventive step when the document is combined with one or more other such documents, such combination being obvious to a person skilled in the art "&" document member of the same patent family		
Date of the actual completion of the international search 14 June, 2005 (14.06.05)		Date of mailing of the international search report 28 June, 2005 (28.06.05)
Name and mailing address of the ISA/ Japanese Patent Office		Authorized officer
Facsimile No.		Telephone No.

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INTERNATIONAL SEARCH REPORT

International application No.

PCT/JP2005/005414

C (Continuation). DOCUMENTS CONSIDERED TO BE RELEVANT

Category*	Citation of document, with indication, where appropriate, of the relevant passages	Relevant to claim No.
Y	JP 8-097673 A (Matsushita Electric Industrial Co., Ltd.), 12 April, 1996 (12.04.96), Par. No. [0012] (Family: none)	6
Y	JP 7-074586 A (Murata Mfg. Co., Ltd.), 17 March, 1995 (17.03.95), Par. Nos. [0004], [0014] & US 005432392 A1 & DE 004400980 A & DE 004400980 A1 & KR 000200179 B	6

Form PCT/ISA/210 (continuation of second sheet) (January 2004)

REFERENCES CITED IN THE DESCRIPTION

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Non-patent literature cited in the description

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- Dansei Hyomenha Kogaku. Information and Communication Engineers. Institute of Electronics, 57 [0094]

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DEVICE MANUFACTURING METHOD
AND BOUNDARY ACOUSTIC WAVE
DEVICE
PUBN-DATE: December 13, 2006

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EUR-CL (EPC): H03H003/04 , H03H009/02

ABSTRACT:

CHG DATE=20061215 STATUS=O>A process for producing a boundary

acoustic wave device having a small variation in frequency is provided. In a process for producing a boundary acoustic wave device that includes a first medium 1, a second medium 2, and a third medium 3 laminated in that order; and electrodes 5 disposed at the interface between the first medium 1 and the second medium 2, the process includes the steps of preparing a laminate including the first medium 1, the second medium 2, and the electrodes 5 disposed at the interface between the first medium 1 and the second medium 2; adjusting the thickness of the second medium 2, after the step of preparing the laminate, to regulate a frequency or the sound velocity of a surface acoustic wave, a pseudo-boundary acoustic wave, or a boundary acoustic wave; after the adjusting step, forming the third medium 3 different from the second medium 2 in terms of the sound velocity with which the boundary acoustic wave propagates therethrough and/or in terms of material.